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N. Thompson  
8-28-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/148,723  
Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

**RESPONSE TO JUNE 18, 2002 EX PARTE QUAYLE OFFICE ACTION**

To: Box Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.  
(Tel. 509-624-4276; Fax 509-838-3424)  
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Spokane, WA 99201-3828

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AUG 26 2002  
TECHNOLOGY CENTER R3700

Responsive to the Ex Parte Quayle Office Action dated June 18, 2002,  
Applicant amends and remarks as follows:

**AMENDMENTS**